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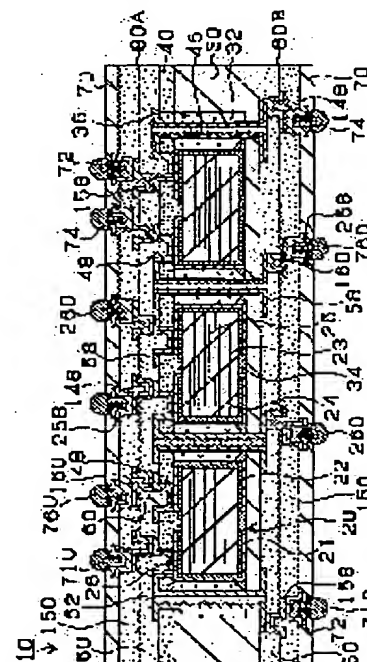
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## (54) PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREFOR

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a printed wiring board which has capacitors inside at high density and is low in defect generation rate and to provide a manufacturing method for the printed wiring board.

**SOLUTION:** In a core board 30, a recessed part 32 is widely formed and capacitors 20 are put therein to incorporate the capacitors 20 at high density. Further, a resin layer is formed to uniformize the thickness since the capacitors 20 in the recessed part 32 become uniform in height, so that the defect generation rate can be lowered. Further, the surfaces of metallized electrodes 21 and 22 are coated with conductive paste 26, so the surfaces of the electrodes 21 and 22 can be made flat and the connectivity to a via hole 60 can be increased.



### LEGAL STATUS

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